

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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High Efficiency Thyristor

 V_{RRM} 1200 V

80 A

1,38 V

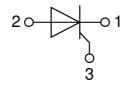
Single Thyristor

Part number

CLA80E1200HF



Backside: anode



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: PLUS247

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

- to perform joint risk and quality assessments;
 the conclusion of quality agreements;
- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

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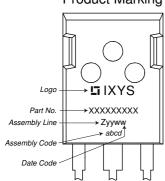


Thyristor					Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Un	
V _{RSM/DSM}	max. non-repetitive reverse/forwa	rd blocking voltage	$T_{VJ} = 25^{\circ}C$			1300	ļ	
V _{RRM/DRM}	max. repetitive reverse/forward bl	<u> </u>	$T_{VJ} = 25^{\circ}C$			1200		
I _{R/D}	reverse current, drain current	$V_{R/D} = 1200 \text{ V}$	$T_{VJ} = 25^{\circ}C$			50	μ	
		$V_{R/D} = 1200 \text{ V}$	$T_{VJ} = 125^{\circ}C$			5	m	
V _T	forward voltage drop	$I_{T} = 80 \text{ A}$	$T_{VJ} = 25^{\circ}C$			1,40		
		$I_{T} = 160 \text{ A}$				1,77	,	
		I _T = 80 A	T _{VJ} = 125°C			1,38		
		$I_{T} = 160 \text{ A}$				1,87		
I _{TAV}	average forward current	T _C = 115°C	T _{vJ} = 150°C			80		
T(RMS)	RMS forward current	180° sine				126		
V _{T0}	threshold voltage		T _{v.i} = 150°C			0,88		
r _T	slope resistance for power log	oss calculation only	***			6,3	m!	
R _{thJC}	thermal resistance junction to cas	e				0,2	K/V	
R _{thCH}	thermal resistance case to heatsi				0,25	-,	K/V	
P _{tot}	total power dissipation		T _C = 25°C		0,20	620	۷	
T _{SM}	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{V.I} = 45^{\circ}C$			900	-	
*TSM	max. Torward barge barrent	t = 8.3 ms; (60 Hz), sine	$V_{R} = 0 V$			970		
		t = 0.5 ms, (60 Hz), sine t = 10 ms; (50 Hz), sine	$T_{VJ} = 150^{\circ}C$			765		
		, , , , , , , , , , , , , , , , , , , ,					į	
101	value for fueing	t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			825	1. 0.1	
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			4,05	kA ²	
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			3,92		
		t = 10 ms; (50 Hz), sine	$T_{VJ} = 150$ °C			2,93	į	
_		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			2,83		
C,	junction capacitance	$V_R = 400 V$ $f = 1 MHz$	$T_{VJ} = 25^{\circ}C$		36		р	
P_{GM}	max. gate power dissipation	$t_P = 30 \mu s$	$T_{C} = 150^{\circ}C$			10	į	
		t _P = 300 μs				5	۷	
P_{GAV}	average gate power dissipation					0,5	٧	
(di/dt) _{cr}	critical rate of rise of current $T_{VJ} = 150 ^{\circ}\text{C}$; f = 50 Hz repetitive, $I_{T} = 240 \text{A}$					150	A/μ	
	$t_P = 200 \mu s; di_G/dt = 0.3 A/\mu s;$							
		$I_{G} = 0.3 A; V = \frac{2}{3} V_{DRM}$ no	on-repet., $I_T = 80 \text{ A}$			500	Α/μ	
(dv/dt) _{cr}	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150$ °C			1000	V/µ	
		R _{GK} = ∞; method 1 (linear voltage	ge rise)					
V _{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			1,5	,	
			$T_{VJ} = -40$ °C			1,6	,	
I _{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			38	m	
u .		J	$T_{VJ} = -40$ °C			80	m	
V _{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^{\circ}C$			0,2	,	
I _{GD}	gate non-trigger current	- D JO - DHW	. ,,,			5	m	
	latching current	t _n = 10 μs	T _{vJ} = 25°C			150	m	
l _L	latering current	r				130	1117	
	holding ourrent	$I_{\rm G} = 0.3 \text{A}; \text{di}_{\rm G}/\text{dt} = 0.3 \text{A}/\mu \text{s}$				100	m	
l _H	holding current	$V_D = 6 V R_{GK} = \infty$	$T_{VJ} = 25 ^{\circ}\text{C}$			100	m	
t _{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25^{\circ}C$			2	μ	
_		$I_{G} = 0.3 \text{ A}; \text{ di}_{G}/\text{dt} = 0.3 \text{ A}/\mu\text{s}$						
t _q	turn-off time $V_R = 100 \text{ V}; I_T = 80 \text{ A}; V = \frac{2}{3} V_{DRM} T_{VJ} = 125 \text{ °C}$				150		μ	
		$di/dt = 20 A/\mu s dv/dt = 20 V/$	/μs t _p = 200 μs	1			1 1 1	



Package	Package PLUS247			Ratings			
Symbol	Definition Conditions		min.	typ.	max.	Unit	
I _{RMS}	RMS current per terminal				70	Α	
T _{VJ}	virtual junction temperature		-40		150	°C	
T _{op}	operation temperature		-40		125	°C	
T _{stg}	storage temperature		-40		150	°C	
Weight				6		g	
F _c	mounting force with clip		20		120	N	
d _{Spp/App}	creepage distance on surface striking distance through air	terminal to terminal	5,5			mm	
d _{Spb/Apb}	creepage distance on surface Striking distance through all	terminal to backside	5,5			mm	

Product Marking



Standard

Part description

C = Thyristor (SCR) L = High Efficiency Thyristor

A = (up to 1200V)

80 = Current Rating [A]

E = Single Thyristor

1200 = Reverse Voltage [V] HF = PLUS247 (3)

Ordering **Ordering Number** Marking on Product **Delivery Mode** Quantity Code No.

CLA80E1200HF

Equivalent Circuits for Simulation			* on die level	$T_{VJ} = 150 ^{\circ}\text{C}$
$I \rightarrow V_0$	R_0	Thyristor		
V _{0 max}	threshold voltage	0,88		V
$R_{0 \text{ max}}$	slope resistance *	3,8		$m\Omega$

CLA80E1200HF

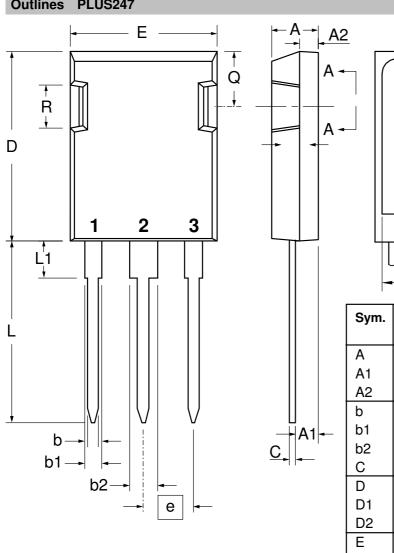
Tube

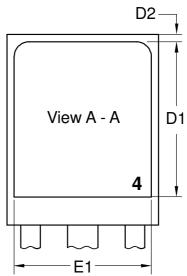
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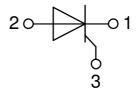


Outlines PLUS247





Sym.	Inches		Millim	eter
	min.	max.	min.	max.
Α	0.190	0.205	4.83	5.21
A1	0.090	0.100	2.29	2.54
A2	0.075	0.085	1.91	2.16
b	0.045	0.055	1.14	1.40
b1	0.075	0.084	1.91	2.13
b2	0.115	0.123	2.92	3.12
С	0.024	0.031	0.61	0.80
D	0.819	0.840	20.80	21.34
D1	0.515	-	13.07	-
D2	0.010	0.053	0.51	1.35
Е	0.620	0.635	15.75	16.13
E1	0.530	-	13.45	-
е	0.215 BSC		5.45 BSC	
L	0.780	0.800	19.81	20.32
L1	0.150	0.170	3.81	4.32
Q	0.220	0.244	5.59	6.20
R	0.170	0.190	4.32	4.83





Thyristor

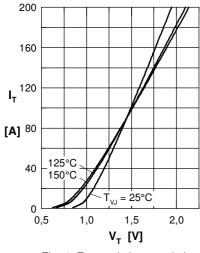


Fig. 1 Forward characteristics

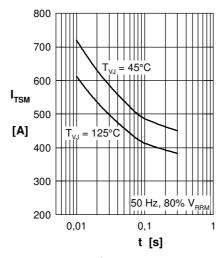


Fig. 2 Surge overload current

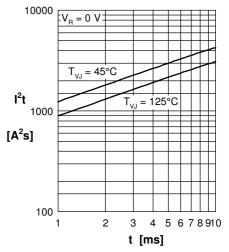


Fig. 3 I²t versus time (1-10 ms)

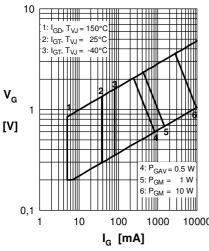


Fig. 4 Gate trigger characteristics

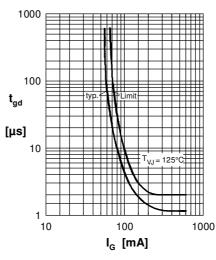


Fig. 5 Gate controlled delay time

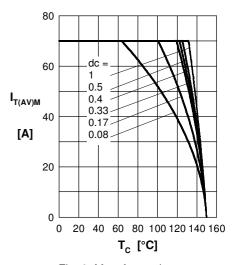


Fig. 6 Max. forward current at case temperature

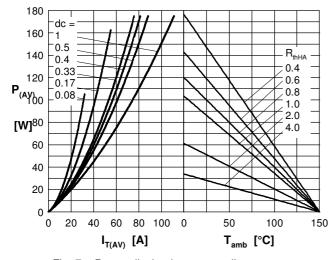


Fig. 7a Power dissipation versus direct output current Fig. 7b and ambient temperature

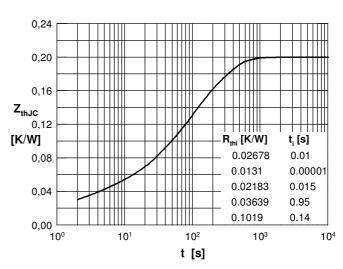


Fig. 8 Transient thermal impedance